FIG. 1

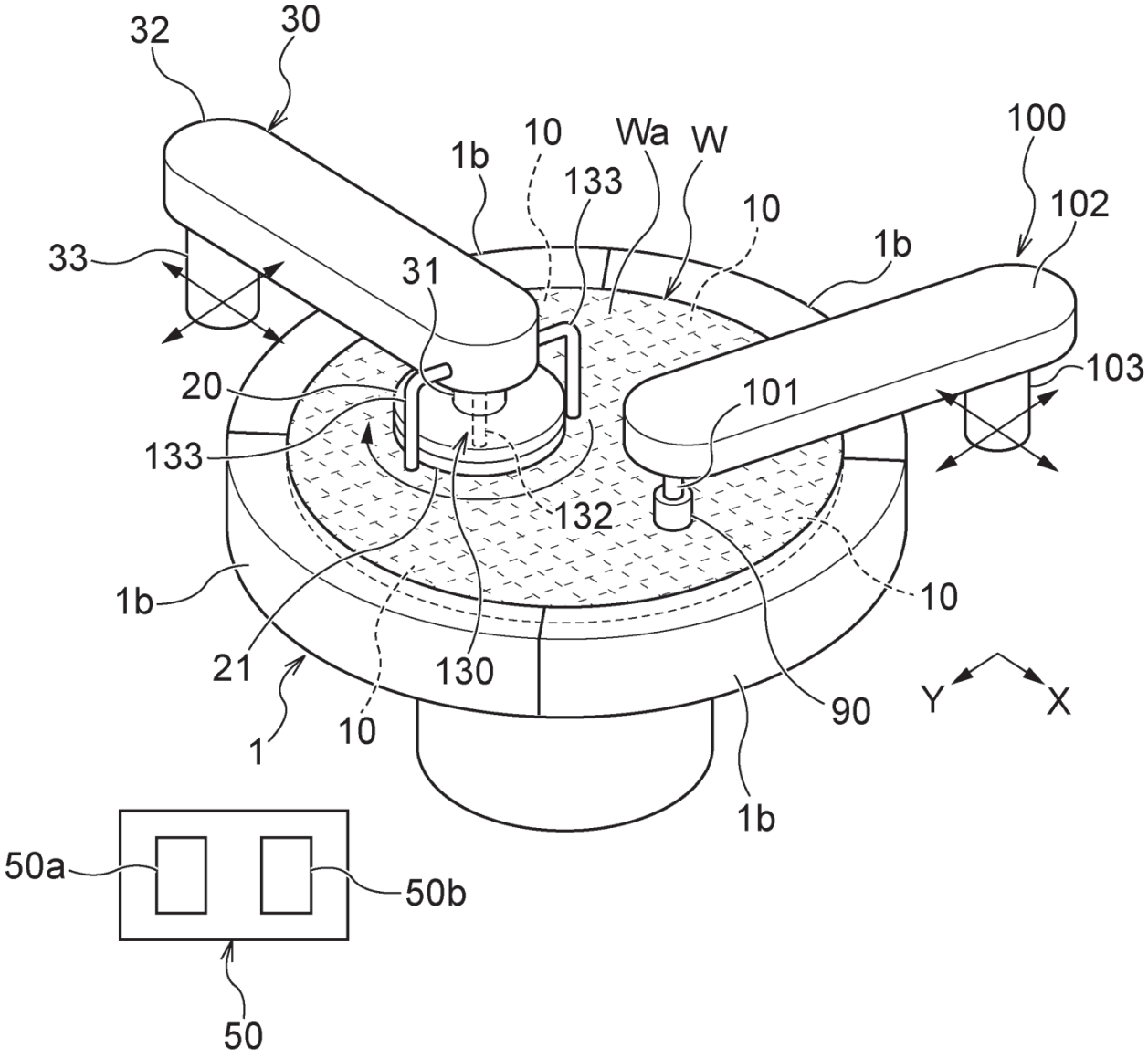

32
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1b
10
Wa
W
133
10
100
102
33
31
1b
103
20
101
133
132
1b
10
21
130
10
90
Y
X
1
1b
50a
50b
50

FIG. 2

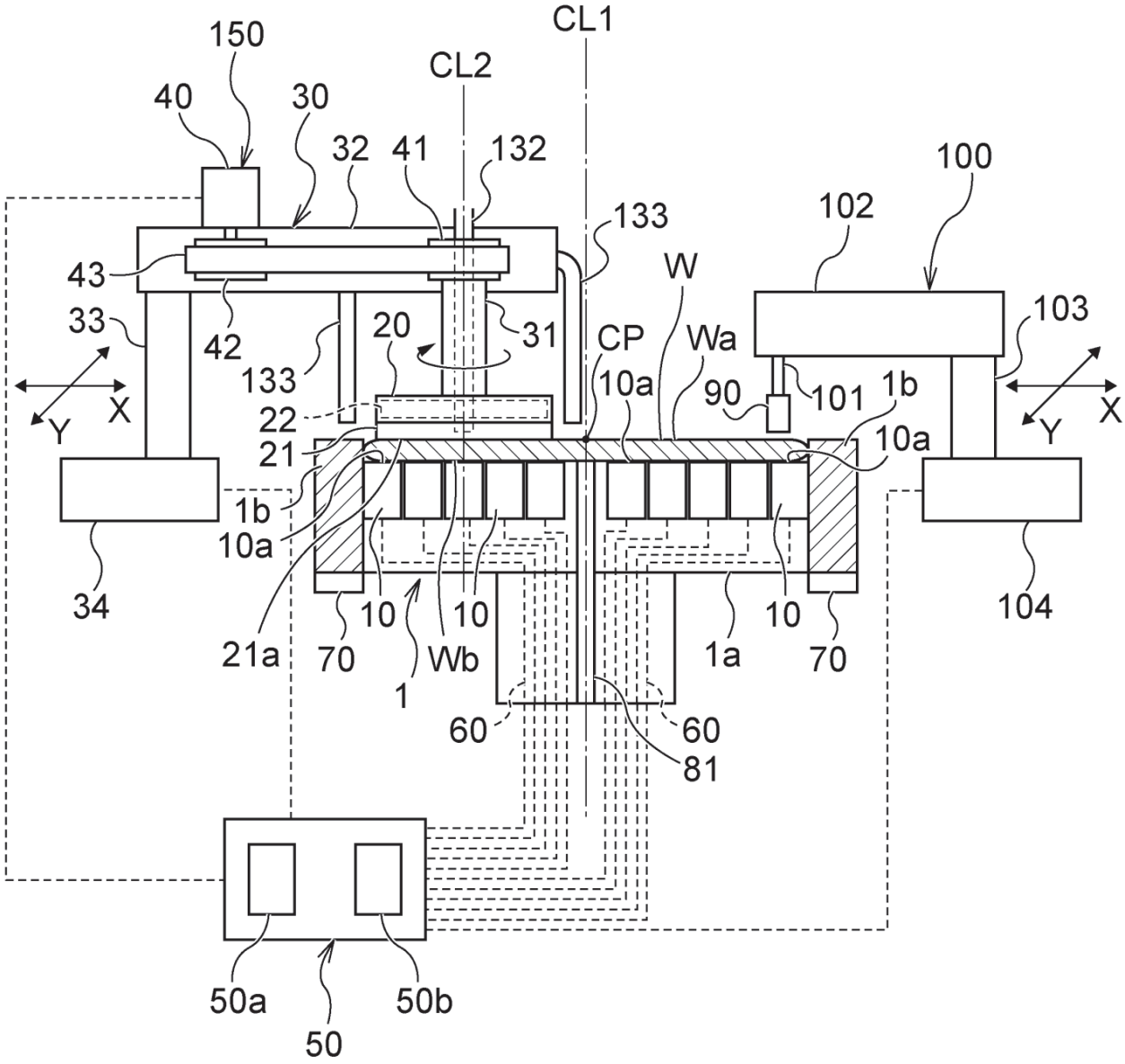

150
CL1
CL2
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30
32
41
132
100
102
133
43
W
103
33
42
20
31
CP
Wa
133
10a
90
101
1b
22
21
10a
Y
X
Y
X
1b
10a
34
104
10
10
10
21a
70
Wb
1a
70
1
60
60
81
50a
50
50b

FIG. 3A

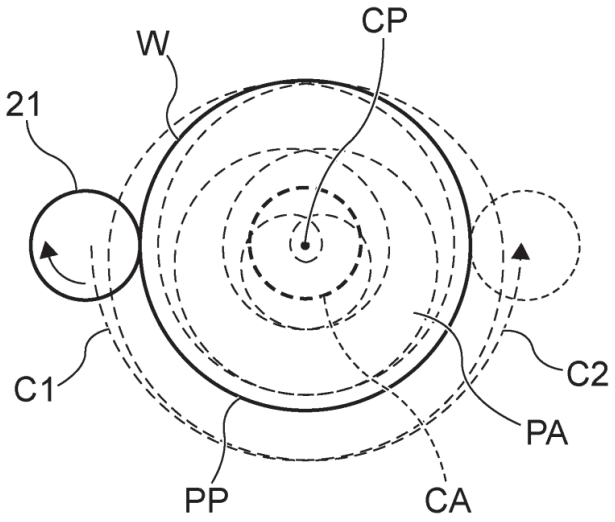


FIG. 3B

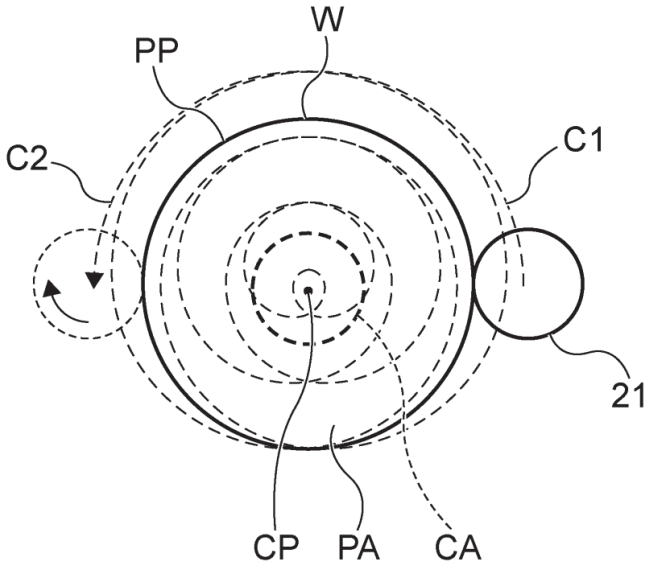


FIG. 4A

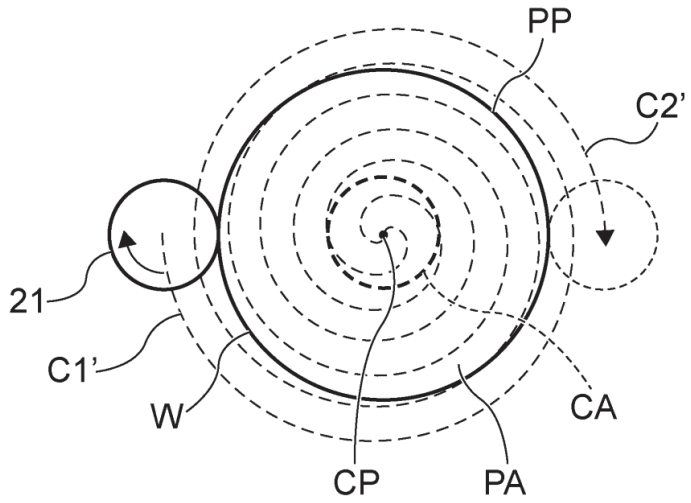


FIG. 4B

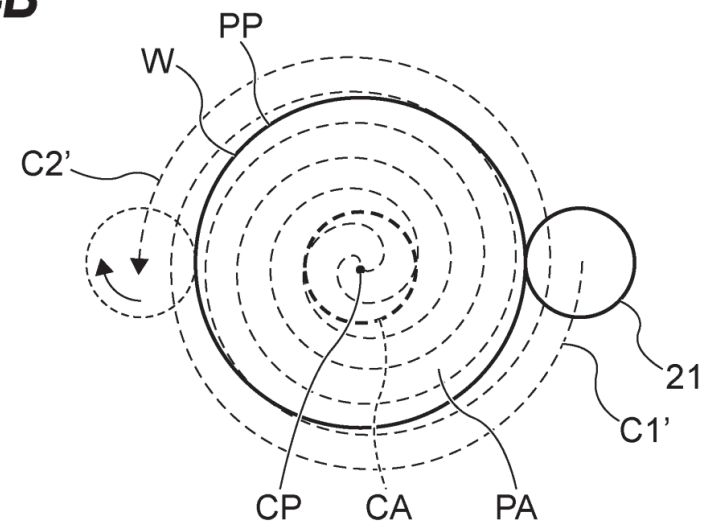


FIG. 5

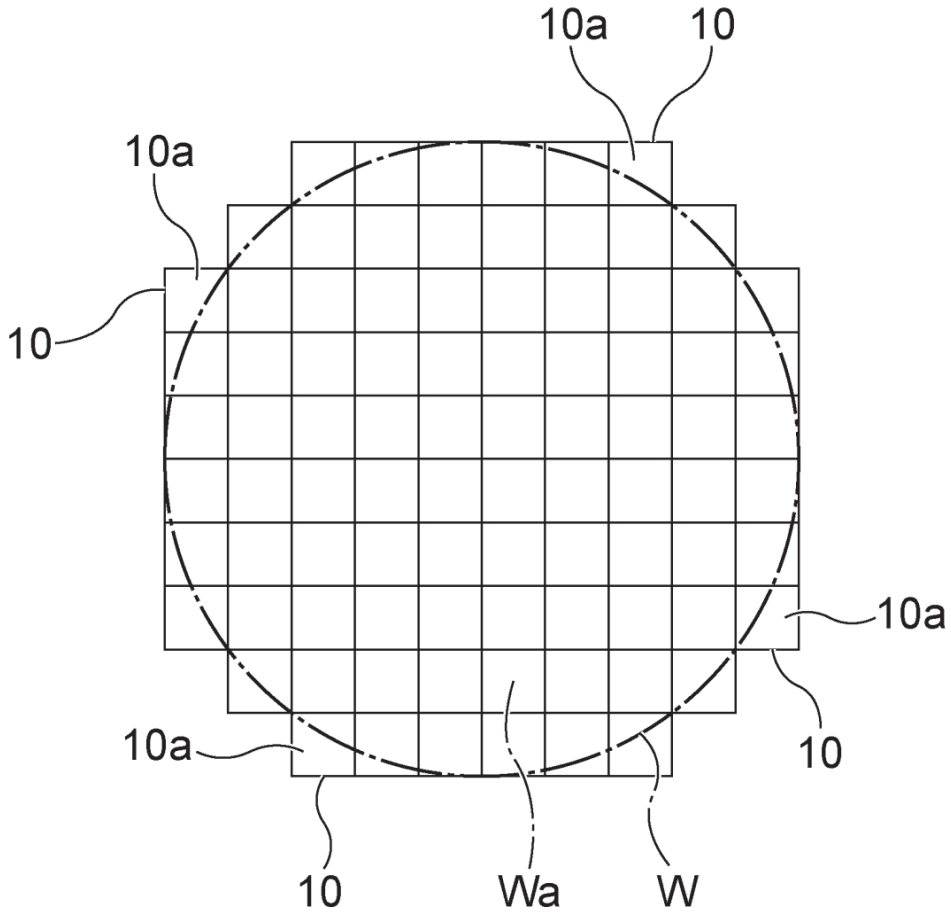


FIG. 6

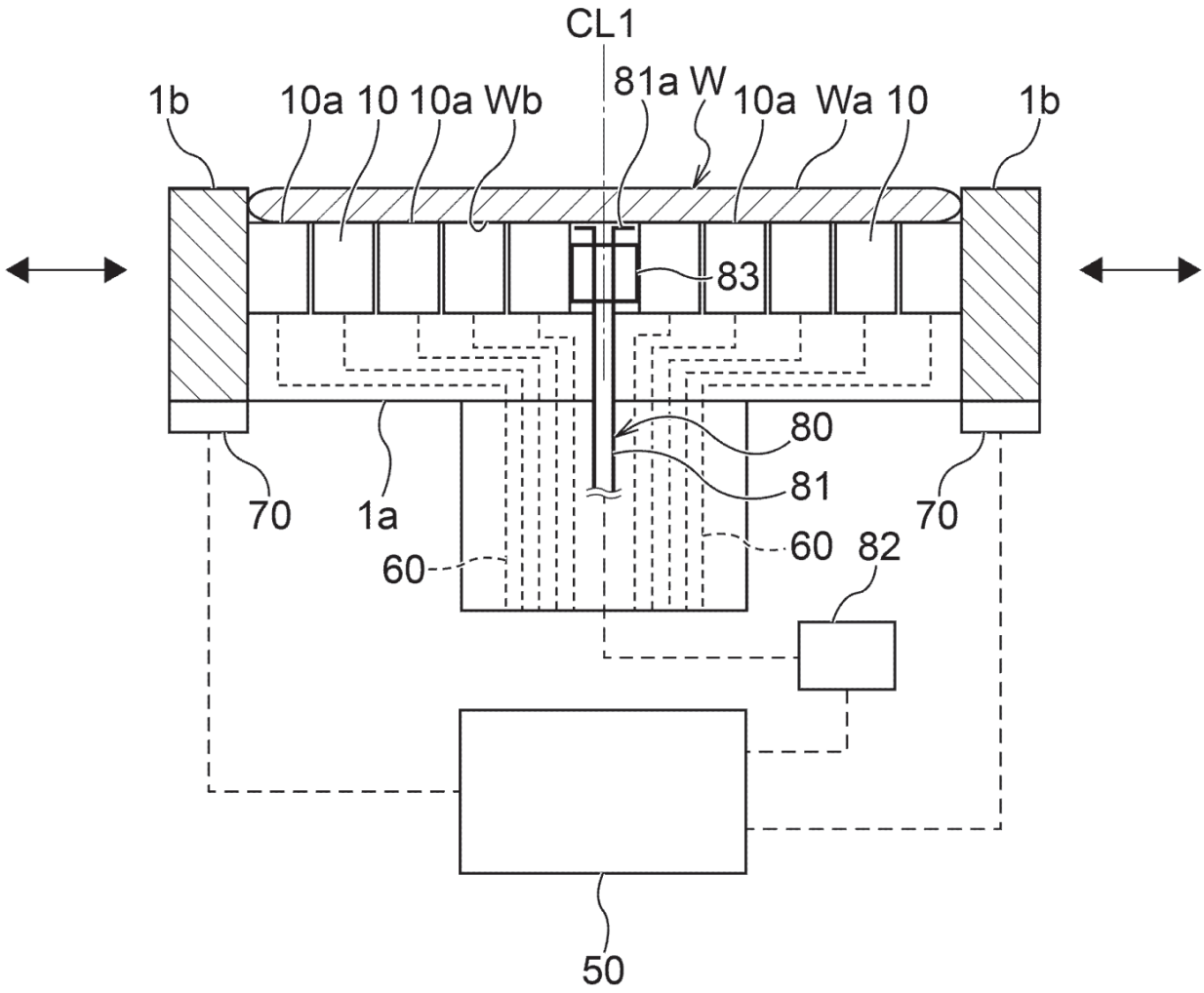


FIG. 7

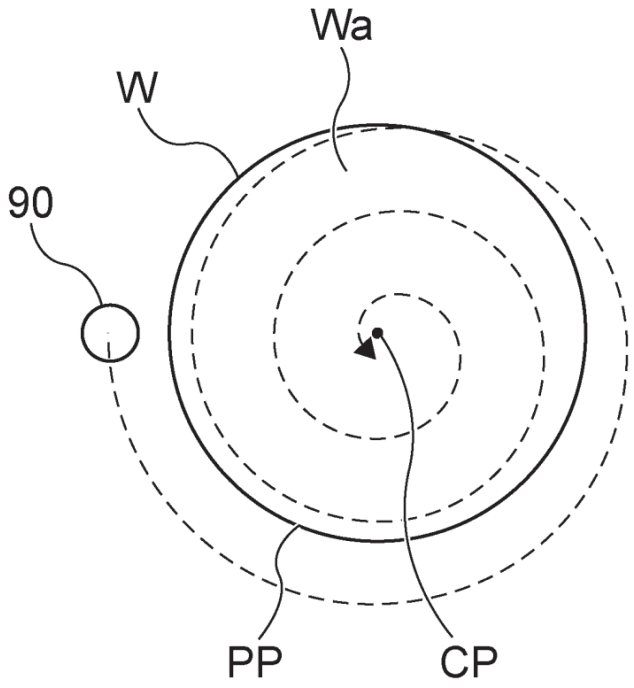


FIG. 8

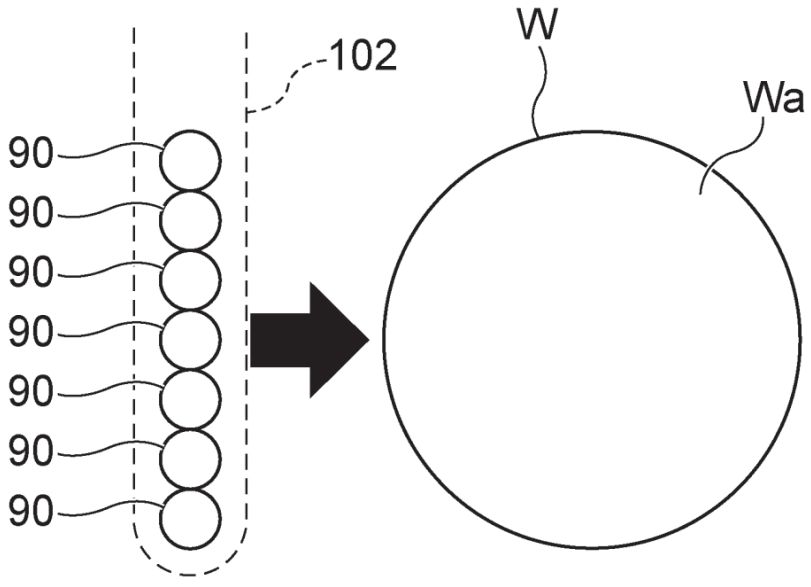


FIG. 9

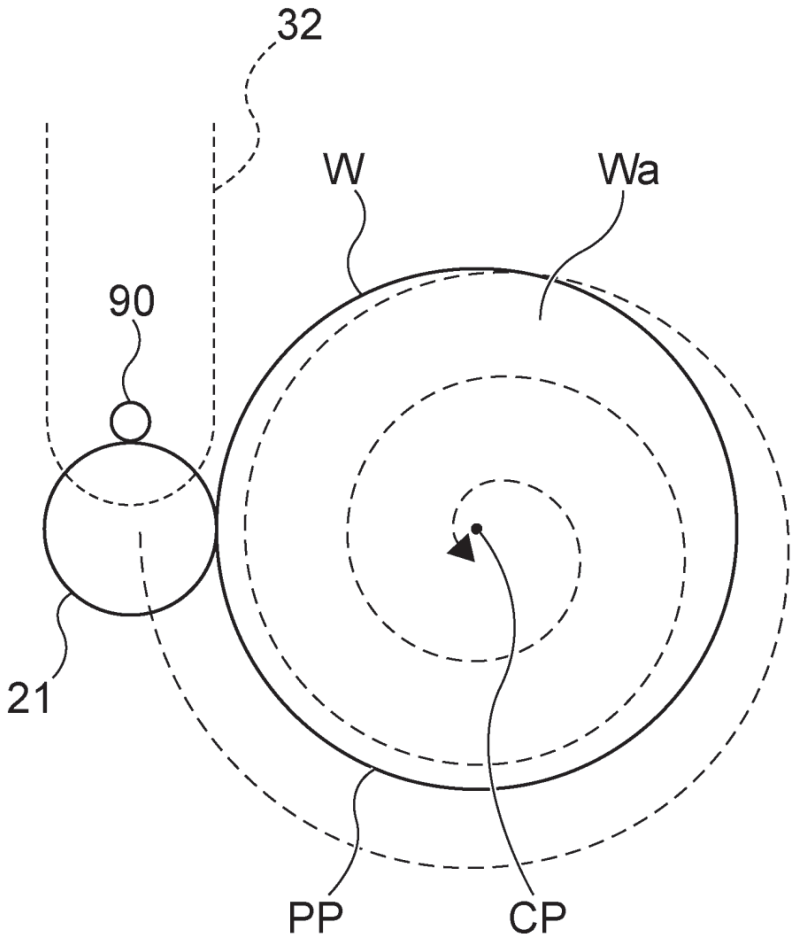


FIG. 10

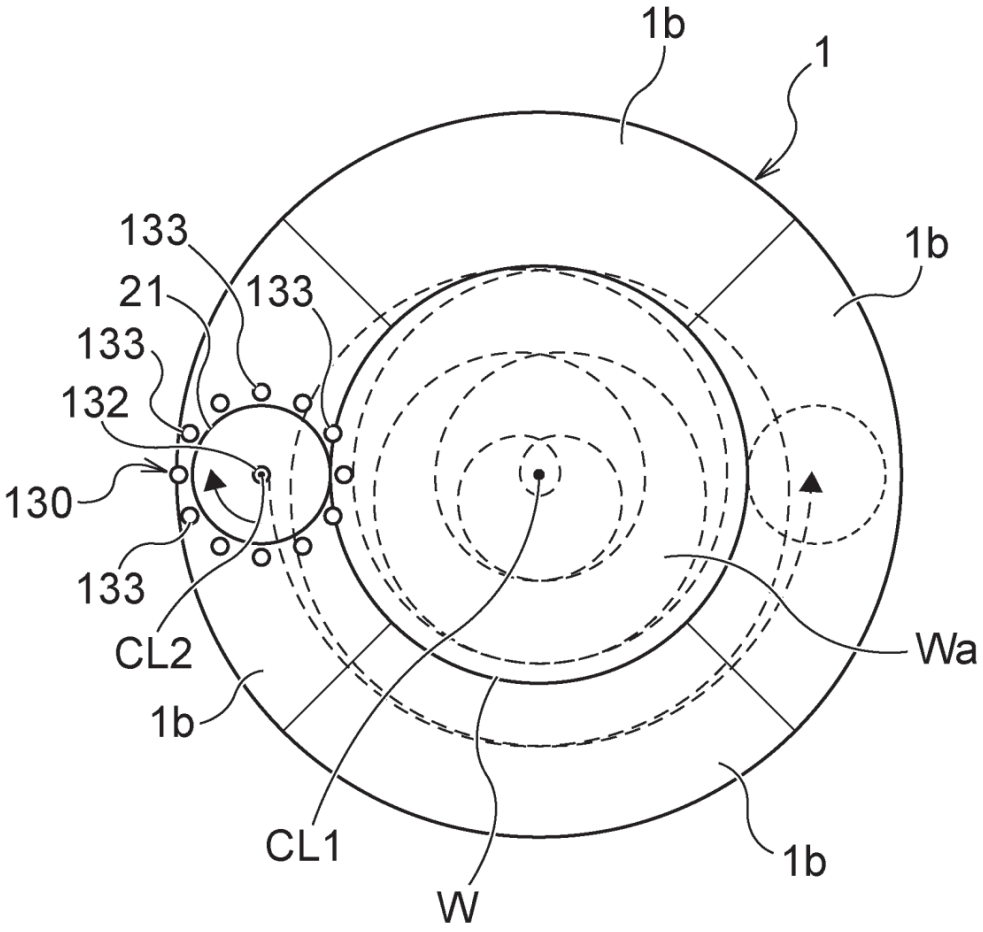


FIG. 11

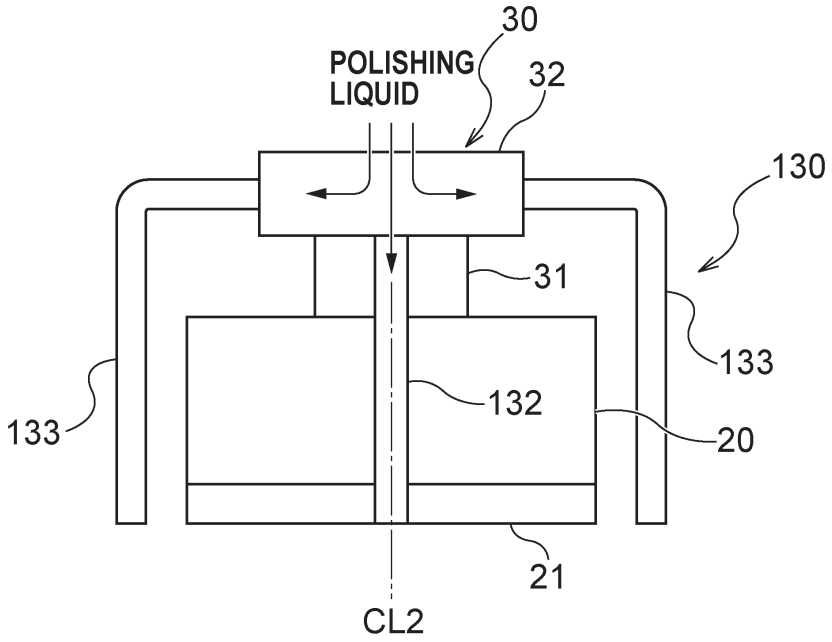


FIG. 12A

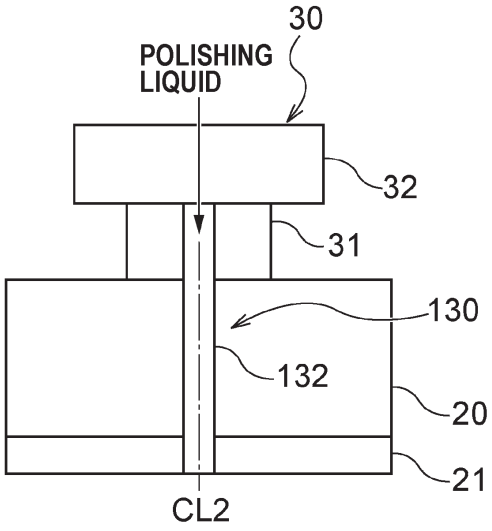


FIG. 12B

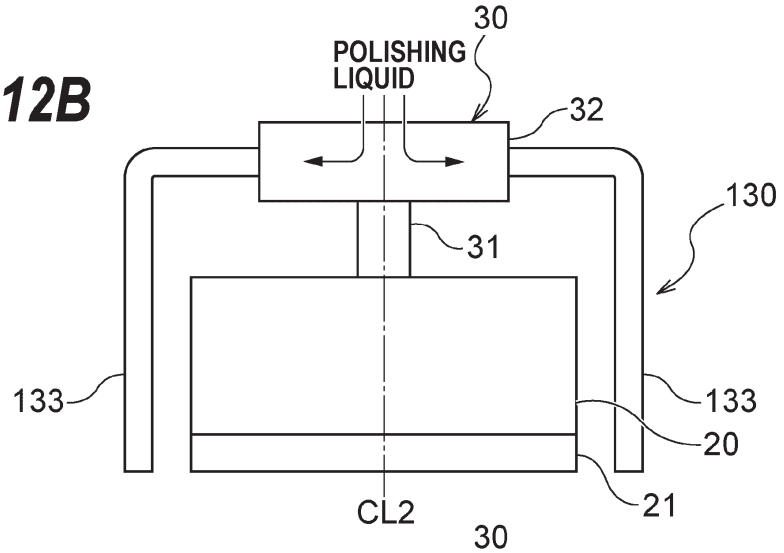


FIG. 12C

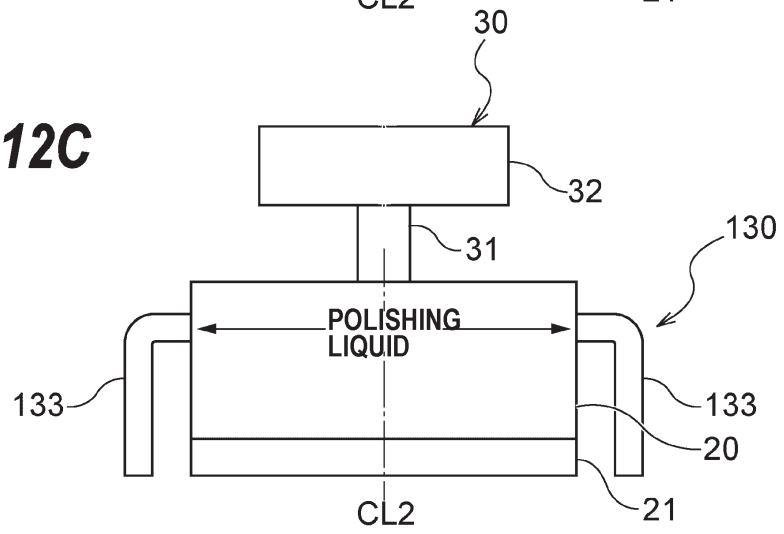


FIG. 13

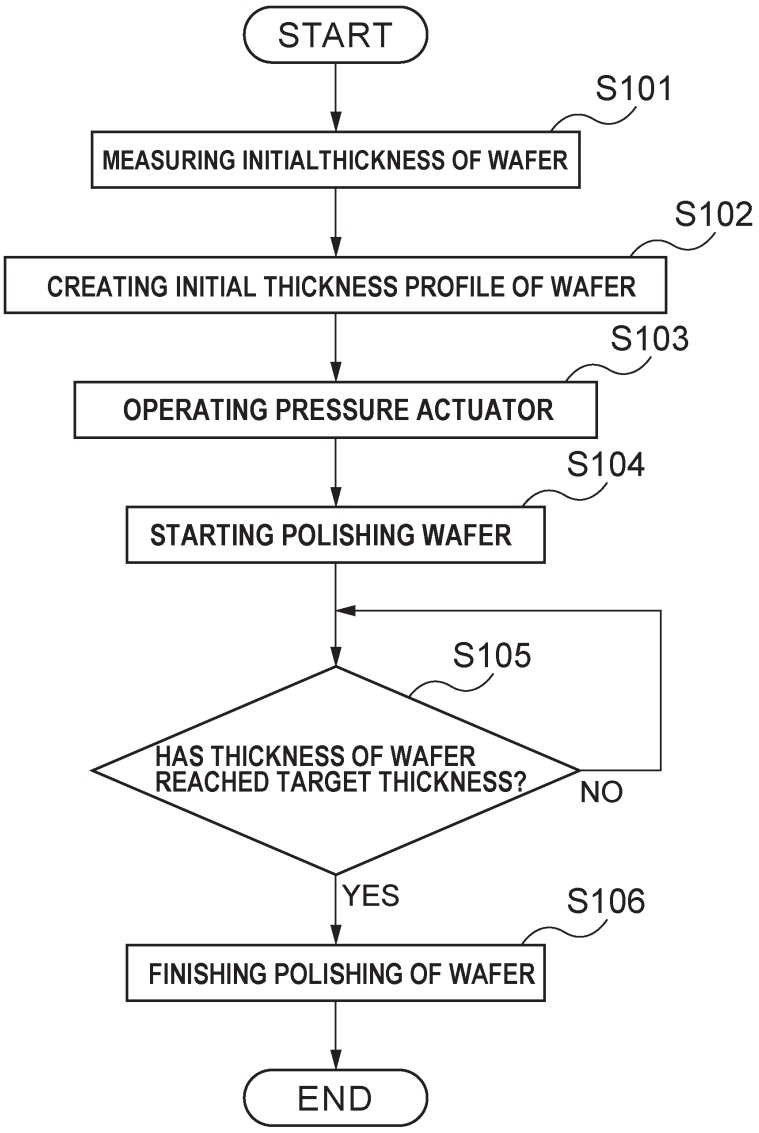

START
S101
MEASURING INITIALTHICKNESS OF WAFER
S102
CREATING INITIAL THICKNESS PROFILE OF WAFER
S103
OPERATING PRESSURE ACTUATOR
S104
STARTING POLISHING WAFER
S105
HAS THICKNESS OF WAFER REACHED TARGET THICKNESS?
NO
YES
S106
FINISHING POLISHING OF WAFER
END

FIG. 14

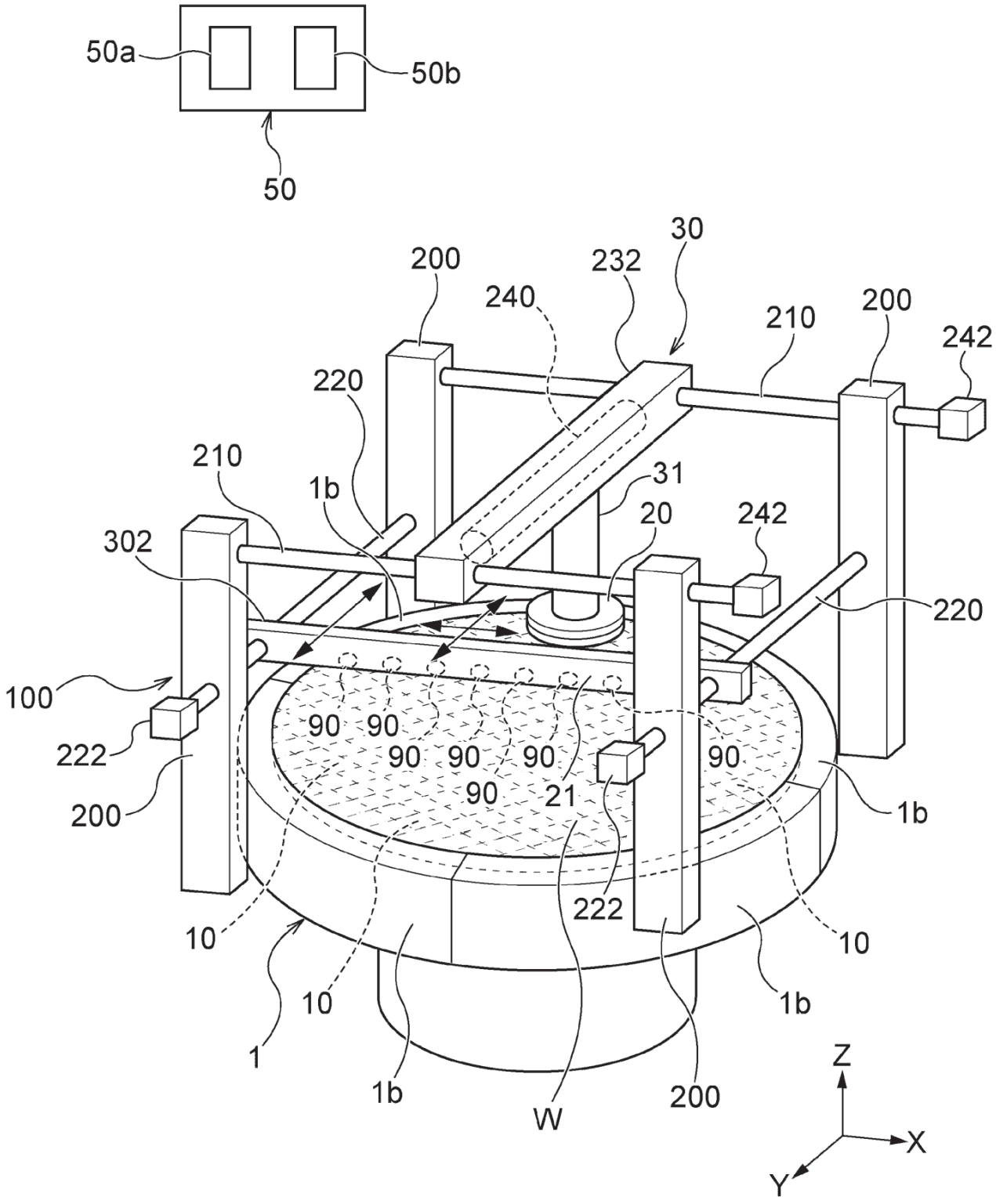

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90
90
90
90
90
90
21
222
1b
10
10
10
1b
1
1b
W
200
Z
X
Y

FIG. 15

